

## English Abstract of Cited Device 1

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**TITLE: POLISHING DEVICE**

### **Abstract:**

**PROBLEM TO BE SOLVED:** To provide a polishing device with which an influence caused by the working accuracy or the like of a retainer ring for pressing a polishing cloth along with the outer peripheral edge of the pressing side thereof to the surface to be polished of a wafer can be reduced in simple structure.

**SOLUTION:** The polishing device for mirror-polishing the surface to be polished of a wafer W is held on a holding panel 22 of a top ring 10 linked to a rotary shaft 12 while pressing that surface to a polishing cloth 16. This device is provided with a retainer ring 40 to which the holding panel 22 is freely inserted and rotated independently of the top ring 10 while being equipped with a pressing plate 42 arranged to surround the outer peripheral edge of the wafer W, when the surface to be polished is pressed onto the polishing cloth 16 for pressing the wafer so that both the pressed sides can be positioned on the same surface, and a roller 50 for locating the placed retainer ring 40 at a prescribed position so that the retainer ring 40 can be rotated with the rotation of a fixed panel.